contact Name Title - Contact Product-Env-Stewards	PC SOCIATION CONNECTING CTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name	2-21.1									als and Mf	g Informat	tion			
Semi   File - Contact   Phone - Contact   Phone - Contact   Phone - Contact   Product-Env-Stewards   Product-Env	pplier Informa	ition				·									
Title - Contact Name Product Env-Stewards Product Enviro Compliance Product Env-Stewards Pro	Company name* Company unique ID				ique ID	Unique			que ID Authority			Response Date*			
Product Env-Stewards Authorized Representative* Title - Representative Product Env-Stewards P	emi											2023-06-	08		
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Numbe	ntact Name			Title - Conta	ct		I	Phone - Contac	t*			Email - 0	Contact*		
Product Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Bffective Date Version Manufacturing Site Weight* UOM  NCP302LSN40T1G ANA UNDERVOLT DETECT 4.0V 2023-06-08 MY1 14.08 mg  Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 Seconds 3	Product-Env-Stewards				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative* Title -				itle - Representative			Phone - Representative*			Email - Representative*				
NCP302LSN40T1G   ANA UNDERVOLT DETECT 4.0V   2023-06-08   MY1   14.08   mg	Product-Env-Stewards Produ				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Anufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester I	Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	V	Veight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  Comments			NCP302I	LSN40T1G	ANA UNDERVOL	LT DETECT 4	.0V	2023-06-08		N	IY1	1	4.08	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Paga	Alloy	STD 020 MSI	I Poting	Dook Proo	oss Pody To	mporatur	May Time at Peak	Tamparati	uro Numi	har of Poflow Cur	Jac
omments					Alloy J-	31D-020 MSL	_ Kaung		ess body 16					ber of Reflow Cyc	ries
		(Sii) - aimealeu	C	U Alloy	1			200		IC	30	second	18   3		
VELL - MAXIMUM TIME AL DEAK TEMPERATURE ONLING SOMERTING IS TO-SU SECONOS		no at neak temperature	during cal	doring is 10.3	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybrominated Biphenyls (Pl	aterial for Cadmium and quantity limit of 0.1% by BB), Polybrominated Diphenyl Ethers (PBDE), an						
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the company that the company tha	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit ide in you believe may apply. If the part is an assembly is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose al applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the				
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.42	mg	Supplier	Silicon (Si)	7440-21-3		0.42	mg
Die Attach	0.11	mg	Supplier	Silver (Ag)	7440-22-4		0.088	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.022	mg
Lead Frame	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.0705	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0069	mg
			Supplier	Iron (Fe)	7439-89-6		0.1358	mg
			Supplier	Copper (Cu)	7440-50-8		5.565	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.04	mg	Supplier	Gold (Au)	7440-57-5		0.04	mg